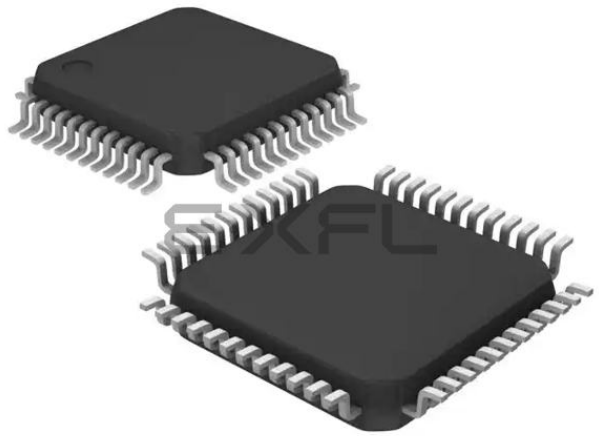

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Details	
Product Status	Active
Core Processor	12V1
Core Size	16-Bit
Speed	25MHz
Connectivity	CANbus, IrDA, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	40
Program Memory Size	192KB (192K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	11K x 8
Voltage - Supply (Vcc/Vdd)	3.13V ~ 5.5V
Data Converters	A/D 16x12b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s9s12ga192f0mlf

1.3.15 Reference Voltage Attenuator (RVA)

- Attenuation of ADC reference voltage with low long-term drift

1.3.16 Digital-to-Analog Converter Module (DAC)

- 1 digital-analog converter channel (per module) with:
  - 8 bit resolution
  - full and reduced output voltage range
  - buffered or unbuffered analog output voltage usable
- operational amplifier stand alone usable

1.3.17 Analog Comparator (ACMP)

- Low offset, low long-term offset drift
- Selectable interrupt on rising, falling, or rising and falling edges of comparator output
- Option to output comparator signal on an external pin
- Option to trigger timer input capture events

1.3.18 On-Chip Voltage Regulator (VREG)

- Linear voltage regulator with bandgap reference
- Low-voltage detect (LVD) with low-voltage interrupt (LVI)
- Power-on reset (POR) circuit
- Low-voltage reset (LVR)

1.3.19 Background Debug (BDM)

- Non-intrusive memory access commands
- Supports in-circuit programming of on-chip nonvolatile memory

1.3.20 Debugger (DBG)

- Trace buffer with depth of 64 entries
- Three comparators (A, B and C)
  - Access address comparisons with optional data comparisons
  - Program counter comparisons
  - Exact address or address range comparisons
- Two types of comparator matches
  - Tagged This matches just before a specific instruction begins execution
  - Force This is valid on the first instruction boundary after a match occurs
- Four trace modes

Table 1-14. 64-Pin LQFP Pinout for S12GN48

	Function <----lowest-----PRIORITY-----highest---->					Power Supply	Internal Pull Resistor	
Package Pin	**Pin**	**2nd Func.**	**3rd Func.**	**4th Func**	**5th Func**		**CTRL**	**Reset State**
57	PS5	MOSI0	—	—	—	V_{DDX}	PERS/PPSS	Up
58	PS6	SCK0	—	—	—	V_{DDX}	PERS/PPSS	Up
59	PS7	API_EXTCLK	ECLK	$\overline{SS0}$	—	V_{DDX}	PERS/PPSS	Up
60	PM0	—	—	—	—	V_{DDX}	PERM/PPSM	Disabled
61	PM1	—	—	—	—	V_{DDX}	PERM/PPSM	Disabled
62	PM2	—	—	—	—	V_{DDX}	PERM/PPSM	Disabled
63	PM3	—	—	—	—	V_{DDX}	PERM/PPSM	Disabled
64	PJ7	KWJ7	—	—	—	V_{DDX}	PERJ/PPSJ	Up

[1] The regular I/O characteristics (see Section A.2, “I/O Characteristics”) apply if the EXTAL/XTAL function is disabled

Table 1-21. 64-Pin LQFP Pinout for S12G96 and S12G128

	Function <----lowest-----PRIORITY-----highest---->					Power Supply	Internal Pull Resistor	
Package Pin	**Pin**	**2nd Func.**	**3rd Func.**	**4th Func**	**5th Func**		**CTRL**	**Reset State**
57	PS5	MOSI0	—	—	—	V_{DDX}	PERS/PPSS	Up
58	PS6	SCK0	—	—	—	V_{DDX}	PERS/PPSS	Up
59	PS7	API_EXTCLK	ECLK	$\overline{SS0}$	—	V_{DDX}	PERS/PPSS	Up
60	PM0	RXCAN	—	—	—	V_{DDX}	PERM/PPSM	Disabled
61	PM1	TXCAN	—	—	—	V_{DDX}	PERM/PPSM	Disabled
62	PM2	RXD2	—	—	—	V_{DDX}	PERM/PPSM	Disabled
63	PM3	TXD2	—	—	—	V_{DDX}	PERM/PPSM	Disabled
64	PJ7	KWJ7	$\overline{SS2}$	—	—	V_{DDX}	PERJ/PPSJ	Up

[1] The regular I/O characteristics (see Section A.2, “I/O Characteristics”) apply if the EXTAL/XTAL function is disabled

1.8.7.3 Pinout 100-Pin LQFP

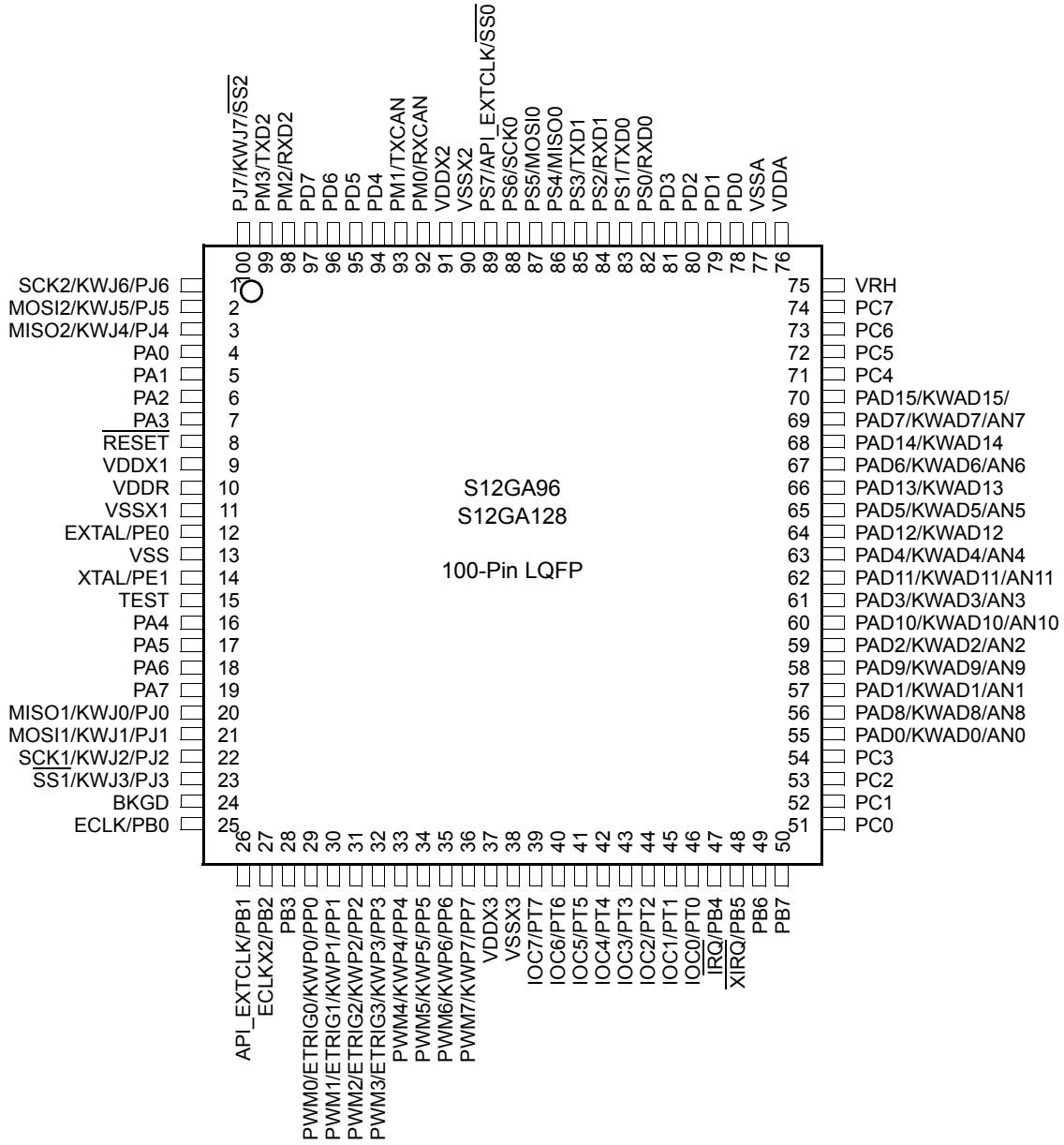

Figure 1-20. 100-Pin LQFP Pinout for S12GA96 and S12GA128

Table 1-26. 48-Pin LQFP Pinout for S12G192 and S12G240

	Function <----lowest-----PRIORITY-----highest---->					Power Supply	Internal Pull Resistor	
Package Pin	Pin	2nd Func.	3rd Func.	4th Func	5th Func		CTRL	Reset State
30	PAD10	KWAD10	AN10	—	—	V_{DDA}	PER0AD/PPS0AD	Disabled
31	PAD3	KWAD3	AN3	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
32	PAD11	KWAD11	AN11	—	—	V_{DDA}	PER0AD/PPS0AD	Disabled
33	PAD4	KWAD4	AN4	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
34	PAD5	KWAD5	AN5	—	—	V_{DDA}	PER1AD/PPS0AD	Disabled
35	PAD6	KWAD6	AN6	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
36	PAD7	KWAD7	AN7	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
37	VDDA	VRH	—	—	—	—	—	—
38	VSSA	—	—	—	—	—	—	—
39	PS0	RXD0	—	—	—	V_{DDX}	PERS/PPSS	Up
40	PS1	TXD0	—	—	—	V_{DDX}	PERS/PPSS	Up
41	PS2	RXD1	—	—	—	V_{DDX}	PERS/PPSS	Up
42	PS3	TXD1	—	—	—	V_{DDX}	PERS/PPSS	Up
43	PS4	MISO0	—	—	—	V_{DDX}	PERS/PPSS	Up
44	PS5	MOSI0	—	—	—	V_{DDX}	PERS/PPSS	Up
45	PS6	SCK0	—	—	—	V_{DDX}	PERS/PPSS	Up
46	PS7	API_EXTCLK	ECLK	$\overline{SS0}$	—	V_{DDX}	PERS/PPSS	Up
47	PM0	RXD2	RXCAN	—	—	V_{DDX}	PERM/PPSM	Disabled
48	PM1	TXD2	TXCAN	—	—	V_{DDX}	PERM/PPSM	Disabled

[1] The regular I/O characteristics (see Section A.2, “I/O Characteristics”) apply if the EXTAL/XTAL function is disabled

2.5.2.6 Wired-Or Mode Register (WOMx)

If the pin is used as an output this register turns off the active-high drive. This allows wired-or type connections of outputs.

2.5.2.7 Interrupt Enable Register (PIEx)

If the pin is used as an interrupt input this register serves as a mask to the interrupt flag to enable/disable the interrupt.

2.5.2.8 Interrupt Flag Register (PIFx)

If the pin is used as an interrupt input this register holds the interrupt flag after a valid pin event.

2.5.2.9 Pin Routing Register (PRRx)

This register allows software re-configuration of the pinouts for specific peripherals in the 20 TSSOP package only.

2.5.2.10 Package Code Register (PKGCR)

This register determines the package in use. Pre programmed by factory.

2.5.3 Pin Configuration Summary

The following table summarizes the effect of the various configuration bits, that is data direction (DDR), output level (IO), pull enable (PE), pull select (PS) on the pin function and pull device [1].

The configuration bit PS is used for two purposes:

1. Configure the sensitive interrupt edge (rising or falling), if interrupt is enabled.
2. Select either a pullup or pulldown device if PE is active.

1.

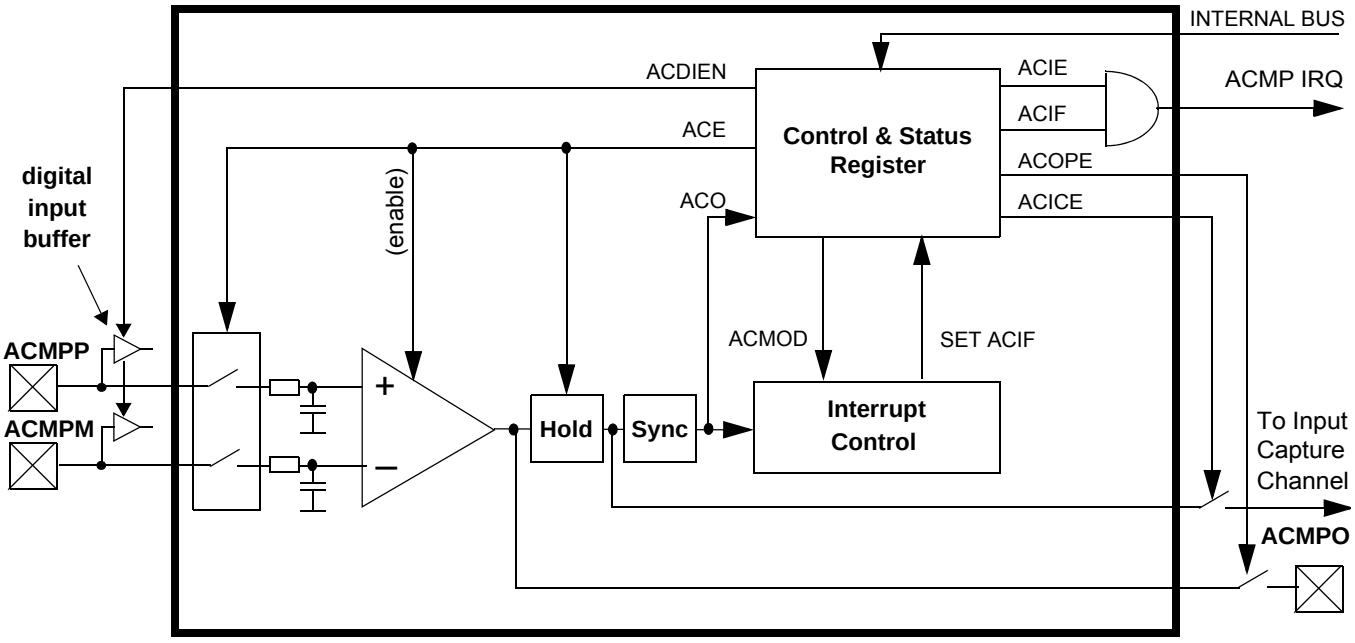

Figure 3-1. ACMP Block Diagram

Figure 3-2.

3.4 External Signals

The ACMP has two analog input signals, ACMPP and ACMPM, and one digital output, ACMPO. The associated pins are defined by the package option.

The ACMPP signal is connected to the non-inverting input of the comparator. The ACMPM signal is connected to the inverting input of the comparator. Each of these signals can accept an input voltage that varies across the full 5V operating voltage range. The module monitors the voltage on these inputs independent of any other functions in use (GPIO, ADC).

The raw comparator output signal can optionally be driven on an external pin.

3.5 Modes of Operation

1. Normal Mode
   The ACMP is operating when enabled and not in STOP mode.
2. Shutdown Mode
   The ACMP is held in shutdown mode either when disabled or during STOP mode. In this case the supply of the analog block is disconnected for power saving. ACMPO drives zero in shutdown mode.

If the interrupt source is unknown (for example, in the case where an interrupt request becomes inactive after the interrupt has been recognized, but prior to the CPU vector request), the vector address supplied to the CPU will default to that of the spurious interrupt vector.

NOTE

Care must be taken to ensure that all interrupt requests remain active until the system begins execution of the applicable service routine; otherwise, the exception request may not get processed at all or the result may be a spurious interrupt request (vector at address (vector base + 0x0080)).

6.4.3 Reset Exception Requests

The INT module supports three system reset exception request types (please refer to the Clock and Reset generator module for details):

1. Pin reset, power-on reset or illegal address reset, low voltage reset (if applicable)
2. Clock monitor reset request
3. COP watchdog reset request

6.4.4 Exception Priority

The priority (from highest to lowest) and address of all exception vectors issued by the INT module upon request by the CPU is shown in Table 6-4.

Table 6-4. Exception Vector Map and Priority

Vector Address[1]	Source
0xFFFE	Pin reset, power-on reset, illegal address reset, low voltage reset (if applicable)
0xFFFC	Clock monitor reset
0xFFFA	COP watchdog reset
(Vector base + 0x00F8)	Unimplemented opcode trap
(Vector base + 0x00F6)	Software interrupt instruction (SWI) or BDM vector request
(Vector base + 0x00F4)	X bit maskable interrupt request (XIRQ or D2D error interrupt)[2]
(Vector base + 0x00F2)	IRQ or D2D interrupt request[3]
(Vector base + 0x00F0–0x0082)	Device specific I bit maskable interrupt sources (priority determined by the low byte of the vector address, in descending order)
(Vector base + 0x0080)	Spurious interrupt

1 16 bits vector address based

2 D2D error interrupt on MCUs featuring a D2D initiator module, otherwise XIRQ pin interrupt

3 D2D interrupt on MCUs featuring a D2D initiator module, otherwise IRQ pin interrupt

If an interrupt is pending when a TRACE1 command is issued, the interrupt stacking operation occurs but no user instruction is executed. Once back in standard BDM firmware execution, the program counter points to the first instruction in the interrupt service routine.

Be aware when tracing through the user code that the execution of the user code is done step by step but all peripherals are free running. Hence possible timing relations between CPU code execution and occurrence of events of other peripherals no longer exist.

Do not trace the CPU instruction BGND used for soft breakpoints. Tracing over the BGND instruction will result in a return address pointing to BDM firmware address space.

When tracing through user code which contains stop or wait instructions the following will happen when the stop or wait instruction is traced:

The CPU enters stop or wait mode and the TRACE1 command can not be finished before leaving the low power mode. This is the case because BDM active mode can not be entered after CPU executed the stop instruction. However all BDM hardware commands except the BACKGROUND command are operational after tracing a stop or wait instruction and still being in stop or wait mode. If system stop mode is entered (all bus masters are in stop mode) no BDM command is operational.

As soon as stop or wait mode is exited the CPU enters BDM active mode and the saved PC value points to the entry of the corresponding interrupt service routine.

In case the handshake feature is enabled the corresponding ACK pulse of the TRACE1 command will be discarded when tracing a stop or wait instruction. Hence there is no ACK pulse when BDM active mode is entered as part of the TRACE1 command after CPU exited from stop or wait mode. All valid commands sent during CPU being in stop or wait mode or after CPU exited from stop or wait mode will have an ACK pulse. The handshake feature becomes disabled only when system stop mode has been reached. Hence after a system stop mode the handshake feature must be enabled again by sending the ACK_ENABLE command.

7.4.11 Serial Communication Time Out

The host initiates a host-to-target serial transmission by generating a falling edge on the BKGD pin. If BKGD is kept low for more than 128 target clock cycles, the target understands that a SYNC command was issued. In this case, the target will keep waiting for a rising edge on BKGD in order to answer the SYNC request pulse. If the rising edge is not detected, the target will keep waiting forever without any time-out limit.

Consider now the case where the host returns BKGD to logic one before 128 cycles. This is interpreted as a valid bit transmission, and not as a SYNC request. The target will keep waiting for another falling edge marking the start of a new bit. If, however, a new falling edge is not detected by the target within 512 clock cycles since the last falling edge, a time-out occurs and the current command is discarded without affecting memory or the operating mode of the MCU. This is referred to as a soft-reset.

If a read command is issued but the data is not retrieved within 512 serial clock cycles, a soft-reset will occur causing the command to be disregarded. The data is not available for retrieval after the time-out has occurred. This is the expected behavior if the handshake protocol is not enabled. In order to allow the data to be retrieved even with a large clock frequency mismatch (between BDM and CPU) when the hardware

storage. The information bits indicate the size of access (word or byte) and the type of access (read or write).

When tracing in Detail Mode, all cycles are traced except those when the CPU is either in a free or opcode fetch cycle.

8.4.5.2.4 Compressed Pure PC Mode

In Compressed Pure PC Mode, the PC addresses of all executed opcodes, including illegal opcodes are stored. A compressed storage format is used to increase the effective depth of the trace buffer. This is achieved by storing the lower order bits each time and using 2 information bits to indicate if a 64 byte boundary has been crossed, in which case the full PC is stored.

Each Trace Buffer row consists of 2 information bits and 18 PC address bits

NOTE:

When tracing is terminated using forced breakpoints, latency in breakpoint generation means that opcodes following the opcode causing the breakpoint can be stored to the trace buffer. The number of opcodes is dependent on program flow. This can be avoided by using tagged breakpoints.

8.4.5.3 Trace Buffer Organization (Normal, Loop1, Detail modes)

ADRH, ADRM, ADRL denote address high, middle and low byte respectively. The numerical suffix refers to the tracing count. The information format for Loop1 and Normal modes is identical. In Detail mode, the address and data for each entry are stored on consecutive lines, thus the maximum number of entries is 32. In this case DBGCNT bits are incremented twice, once for the address line and once for the data line, on each trace buffer entry. In Detail mode CINF comprises of R/W and size access information (CRW and CSZ respectively).

Single byte data accesses in Detail Mode are always stored to the low byte of the trace buffer (DATAL) and the high byte is cleared. When tracing word accesses, the byte at the lower address is always stored to trace buffer byte1 and the byte at the higher address is stored to byte0.

Table 8-37. Trace Buffer Organization (Normal,Loop1,Detail modes)

Mode	Entry Number	4-bits	8-bits	8-bits
		Field 2	Field 1	Field 0
Detail Mode	Entry 1	CINF1,ADRH1	ADRM1	ADRL1
		0	DATAH1	DATAL1
	Entry 2	CINF2,ADRH2	ADRM2	ADRL2
		0	DATAH2	DATAL2
Normal/Loop1 Modes	Entry 1	PCH1	PCM1	PCL1
	Entry 2	PCH2	PCM2	PCL2

11.2 Signal Description

This section lists all inputs to the ADC10B8C block.

11.2.1 Detailed Signal Descriptions

11.2.1.1 AN*x* (*x* = 7, 6, 5, 4, 3, 2, 1, 0)

This pin serves as the analog input Channel *x*. It can also be configured as digital port or external trigger for the ATD conversion.

11.2.1.2 ETRIG3, ETRIG2, ETRIG1, ETRIG0

These inputs can be configured to serve as an external trigger for the ATD conversion.

Refer to device specification for availability and connectivity of these inputs!

11.2.1.3 VRH, VRL

VRH is the high reference voltage, VRL is the low reference voltage for ATD conversion.

11.2.1.4 VDDA, VSSA

These pins are the power supplies for the analog circuitry of the ADC10B8C block.

11.3 Memory Map and Register Definition

This section provides a detailed description of all registers accessible in the ADC10B8C.

11.3.1 Module Memory Map

Figure 11-2 gives an overview on all ADC10B8C registers.

NOTE

Register Address = Base Address + Address Offset, where the Base Address is defined at the MCU level and the Address Offset is defined at the module level.

Address	Name		Bit 7	6	5	4	3	2	1	Bit 0
0x0000	ATDCTL0	R W	Reserved	0	0	0	WRAP3	WRAP2	WRAP1	WRAP0
0x0001	ATDCTL1	R W	ETRIGSEL	SRES1	SRES0	SMP_DIS	ETRIGCH3	ETRIGCH2	ETRIGCH1	ETRIGCH0
0x0002	ATDCTL2	R W	0	AFFC	Reserved	ETRIGLE	ETRIGP	ETRIGE	ASCIE	ACMPIE

= Unimplemented or Reserved

Figure 11-2. ADC10B8C Register Summary (Sheet 1 of 2)

[1]If only AN0 should be converted use MULT=0.

12.3.2.2 ATD Control Register 1 (ATDCTL1)

Writes to this register will abort current conversion sequence.

Module Base + 0x0001

	7	6	5	4	3	2	1	0
R W	ETRIGSEL	SRES1	SRES0	SMP_DIS	ETRIGCH3	ETRIGCH2	ETRIGCH1	ETRIGCH0
Reset	0	0	1	0	1	1	1	1

Figure 12-4. ATD Control Register 1 (ATDCTL1)

Read: Anytime

Write: Anytime

Table 12-3. ATDCTL1 Field Descriptions

Field	Description
7 ETRIGSEL	**External Trigger Source Select** — This bit selects the external trigger source to be either one of the AD channels or one of the ETRIG3-0 inputs. See device specification for availability and connectivity of ETRIG3-0 inputs. If a particular ETRIG3-0 input option is not available, writing a 1 to ETRISEL only sets the bit but has no effect, this means that one of the AD channels (selected by ETRIGCH3-0) is configured as the source for external trigger. The coding is summarized in Table 12-5.
6–5 SRES[1:0]	**A/D Resolution Select** — These bits select the resolution of A/D conversion results. See Table 12-4 for coding.
4 SMP_DIS	**Discharge Before Sampling Bit** 0 No discharge before sampling. 1 The internal sample capacitor is discharged before sampling the channel. This adds 2 ATD clock cycles to the sampling time. This can help to detect an open circuit instead of measuring the previous sampled channel.
3–0 ETRIGCH[3:0]	**External Trigger Channel Select** — These bits select one of the AD channels or one of the ETRIG3-0 inputs as source for the external trigger. The coding is summarized in Table 12-5.

Table 12-4. A/D Resolution Coding

SRES1	SRES0	A/D Resolution
0	0	8-bit data
0	1	10-bit data
1	0	12-bit data
1	1	Reserved

19.1.3 Block Diagram

Figure 19-1 shows the block diagram for the 8-bit up to 8-channel scalable PWM block.

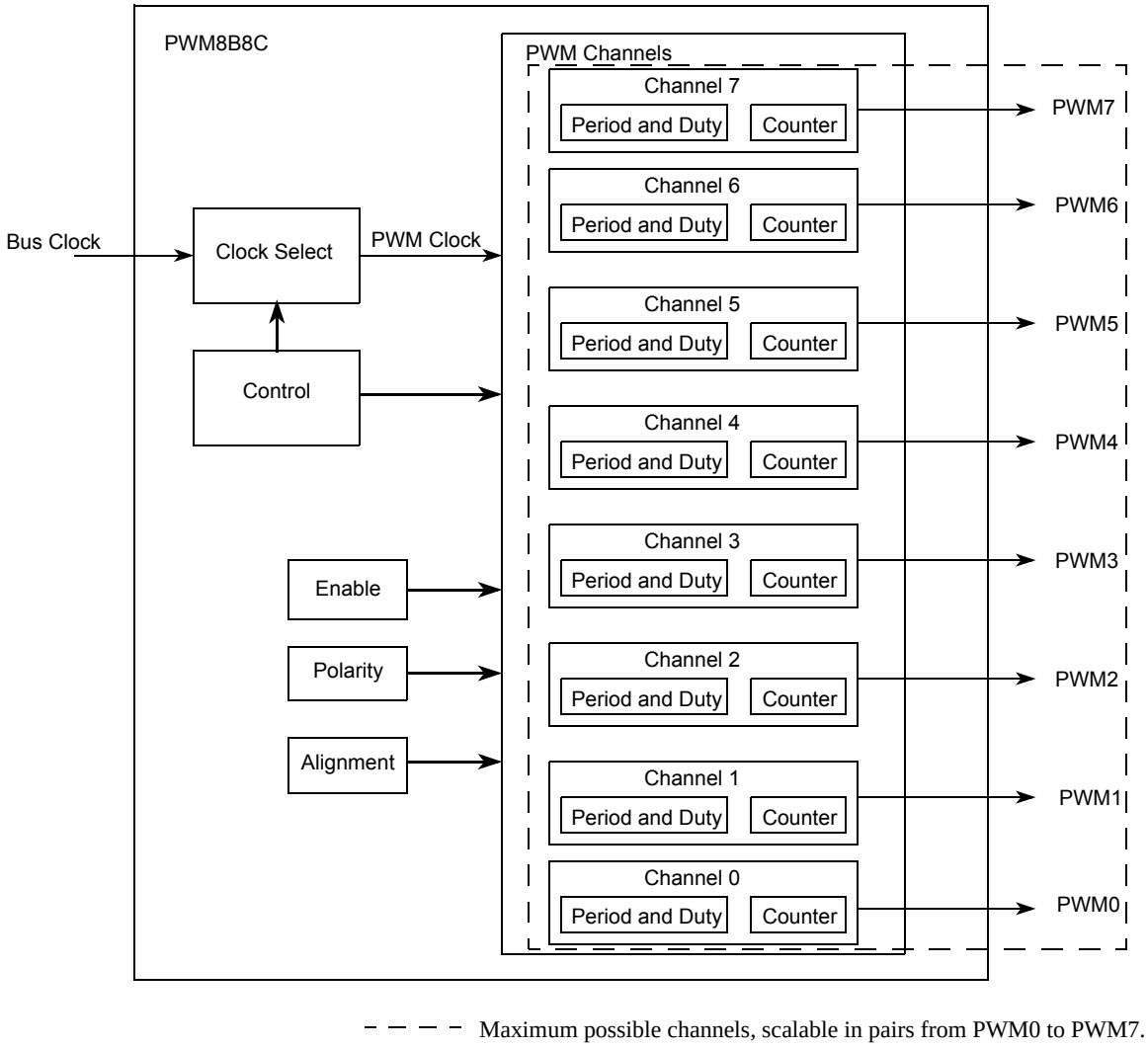

Figure 19-1. Scalable PWM Block Diagram

19.2 External Signal Description

The scalable PWM module has a selected number of external pins. Refer to device specification for exact number.

19.2.1 PWM7 - PWM0 — PWM Channel 7 - 0

Those pins serve as waveform output of PWM channel 7 - 0.

21.2.2 MISO — Master In/Slave Out Pin

This pin is used to transmit data out of the SPI module when it is configured as a slave and receive data when it is configured as master.

21.2.3 $\overline{SS}$ — Slave Select Pin

This pin is used to output the select signal from the SPI module to another peripheral with which a data transfer is to take place when it is configured as a master and it is used as an input to receive the slave select signal when the SPI is configured as slave.

21.2.4 SCK — Serial Clock Pin

In master mode, this is the synchronous output clock. In slave mode, this is the synchronous input clock.

21.3 Memory Map and Register Definition

This section provides a detailed description of address space and registers used by the SPI.

21.3.1 Module Memory Map

The memory map for the SPI is given in Figure 21-2. The address listed for each register is the sum of a base address and an address offset. The base address is defined at the SoC level and the address offset is defined at the module level. Reads from the reserved bits return zeros and writes to the reserved bits have no effect.

Register Name		Bit 7	6	5	4	3	2	1	Bit 0
0x0000 SPICR1	R	SPIE	SPE	SPTIE	MSTR	CPOL	CPHA	SSOE	LSBFE
	W								
0x0001 SPICR2	R	0	XFRW	0	MODFEN	BIDIROE	0	SPISWAI	SPC0
	W								
0x0002 SPIBR	R	0	SPPR2	SPPR1	SPPR0	0	SPR2	SPR1	SPR0
	W								
0x0003 SPISR	R	SPIF	0	SPTEF	MODF	0	0	0	0
	W								
0x0004 SPIDRH	R	R15	R14	R13	R12	R11	R10	R9	R8
	W	T15	T14	T13	T12	T11	T10	T9	T8
		= Unimplemented or Reserved							

Figure 21-2. SPI Register Summary

The main element of the SPI system is the SPI data register. The n-bit[1] data register in the master and the n-bit[1] data register in the slave are linked by the MOSI and MISO pins to form a distributed 2n-bit[1] register. When a data transfer operation is performed, this 2n-bit[1] register is serially shifted n[1] bit positions by the S-clock from the master, so data is exchanged between the master and the slave. Data written to the master SPI data register becomes the output data for the slave, and data read from the master SPI data register after a transfer operation is the input data from the slave.

A read of SPISR with SPTEF = 1 followed by a write to SPIDR puts data into the transmit data register. When a transfer is complete and SPIF is cleared, received data is moved into the receive data register. This data register acts as the SPI receive data register for reads and as the SPI transmit data register for writes. A common SPI data register address is shared for reading data from the read data buffer and for writing data to the transmit data register.

The clock phase control bit (CPHA) and a clock polarity control bit (CPOL) in the SPI control register 1 (SPICR1) select one of four possible clock formats to be used by the SPI system. The CPOL bit simply selects a non-inverted or inverted clock. The CPHA bit is used to accommodate two fundamentally different protocols by sampling data on odd numbered SCK edges or on even numbered SCK edges (see Section 21.4.3, “Transmission Formats”).

The SPI can be configured to operate as a master or as a slave. When the MSTR bit in SPI control register1 is set, master mode is selected, when the MSTR bit is clear, slave mode is selected.

NOTE

A change of CPOL or MSTR bit while there is a received byte pending in the receive shift register will destroy the received byte and must be avoided.

21.4.1 Master Mode

The SPI operates in master mode when the MSTR bit is set. Only a master SPI module can initiate transmissions. A transmission begins by writing to the master SPI data register. If the shift register is empty, data immediately transfers to the shift register. Data begins shifting out on the MOSI pin under the control of the serial clock.

- Serial clock

  The SPR2, SPR1, and SPR0 baud rate selection bits, in conjunction with the SPPR2, SPPR1, and SPPR0 baud rate preselection bits in the SPI baud rate register, control the baud rate generator and determine the speed of the transmission. The SCK pin is the SPI clock output. Through the SCK pin, the baud rate generator of the master controls the shift register of the slave peripheral.
- MOSI, MISO pin

  In master mode, the function of the serial data output pin (MOSI) and the serial data input pin (MISO) is determined by the SPC0 and BIDIROE control bits.
- $\overline{SS}$ pin

  If MODFEN and SSOE are set, the $\overline{SS}$ pin is configured as slave select output. The $\overline{SS}$ output becomes low during each transmission and is high when the SPI is in idle state.

1. n depends on the selected transfer width, please refer to Section 21.3.2.2, “SPI Control Register 2 (SPICR2)

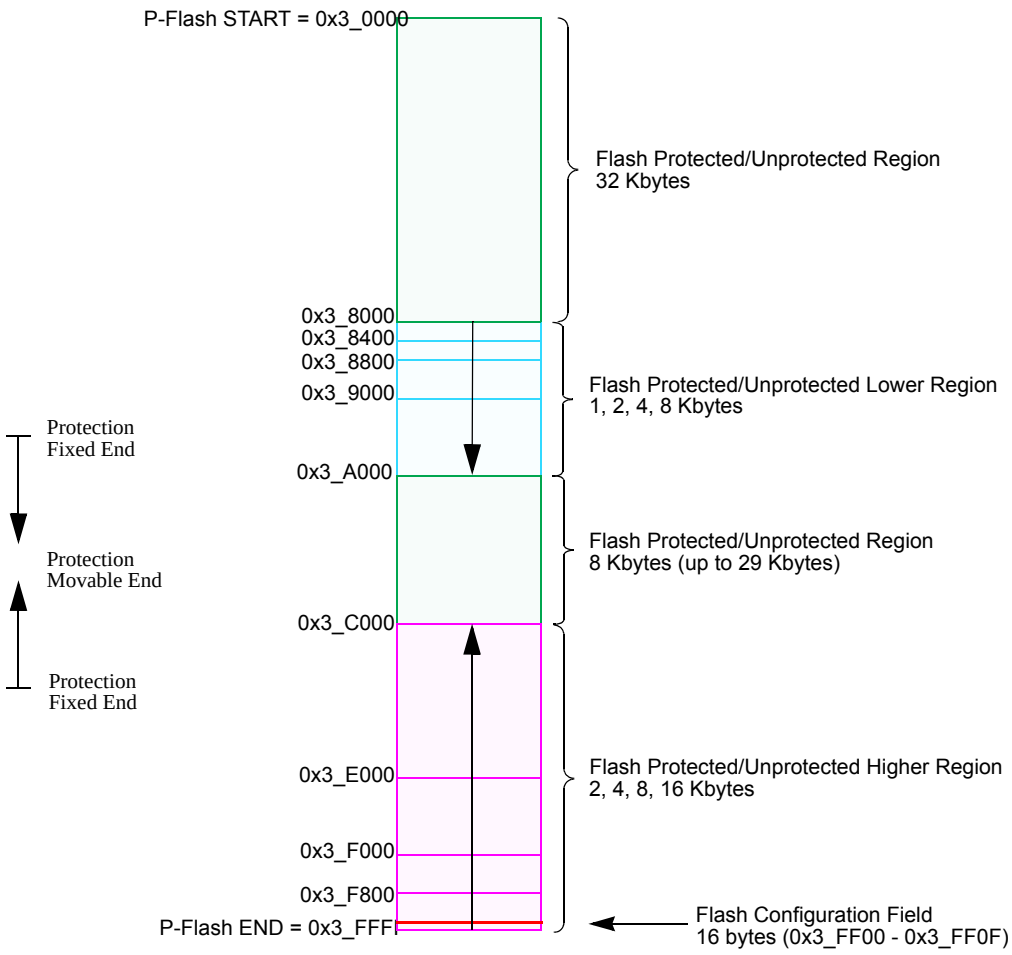

Figure 27-2. P-Flash Memory Map

Table 27-5. Program IFR Fields

Global Address	Size (Bytes)	Field Description
0x0_4000 – 0x0_4007	8	Reserved
0x0_4008 – 0x0_40B5	174	Reserved
0x0_40B6 – 0x0_40B7	2	Version ID[1]
0x0_40B8 – 0x0_40BF	8	Reserved
0x0_40C0 – 0x0_40FF	64	Program Once Field Refer to Section 27.4.6.6, “Program Once Command”

[1] Used to track firmware patch versions, see Section 27.4.2

- Single bit fault correction and double bit fault detection within a 32-bit double word during read operations
- Automated program and erase algorithm with verify and generation of ECC parity bits
- Fast sector erase and phrase program operation
- Ability to read the P-Flash memory while programming a word in the EEPROM memory
- Flexible protection scheme to prevent accidental program or erase of P-Flash memory

30.1.2.2 EEPROM Features

- 4Kbytes of EEPROM memory composed of one 4 Kbyte Flash block divided into 1024 sectors of 4 bytes
- Single bit fault correction and double bit fault detection within a word during read operations
- Automated program and erase algorithm with verify and generation of ECC parity bits
- Fast sector erase and word program operation
- Protection scheme to prevent accidental program or erase of EEPROM memory
- Ability to program up to four words in a burst sequence

30.1.2.3 Other Flash Module Features

- No external high-voltage power supply required for Flash memory program and erase operations
- Interrupt generation on Flash command completion and Flash error detection
- Security mechanism to prevent unauthorized access to the Flash memory

30.1.3 Block Diagram

The block diagram of the Flash module is shown in Figure 30-1.

Table 30-15. FSTAT Field Descriptions (continued)

Field	Description
3 MGBUSY	**Memory Controller Busy Flag** — The MGBUSY flag reflects the active state of the Memory Controller. 0 Memory Controller is idle 1 Memory Controller is busy executing a Flash command (CCIF = 0)
2 RSVD	**Reserved Bit** — This bit is reserved and always reads 0.
1–0 MGSTAT[1:0]	**Memory Controller Command Completion Status Flag** — One or more MGSTAT flag bits are set if an error is detected during execution of a Flash command or during the Flash reset sequence. See Section 30.4.6, “Flash Command Description,” and Section 30.6, “Initialization” for details.

30.3.2.8 Flash Error Status Register (FERSTAT)

The FERSTAT register reflects the error status of internal Flash operations.

Offset Module Base + 0x0007

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	DFDIF	SFDIF
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 30-12. Flash Error Status Register (FERSTAT)

All flags in the FERSTAT register are readable and only writable to clear the flag.

Table 30-16. FERSTAT Field Descriptions

Field	Description
1 DFDIF	**Double Bit Fault Detect Interrupt Flag** — The setting of the DFDIF flag indicates that a double bit fault was detected in the stored parity and data bits during a Flash array read operation or that a Flash array read operation returning invalid data was attempted on a Flash block that was under a Flash command operation.[1] The DFDIF flag is cleared by writing a 1 to DFDIF. Writing a 0 to DFDIF has no effect on DFDIF.[2] 0 No double bit fault detected 1 Double bit fault detected or a Flash array read operation returning invalid data was attempted while command running
0 SFDIF	**Single Bit Fault Detect Interrupt Flag** — With the IGNSF bit in the FCNFG register clear, the SFDIF flag indicates that a single bit fault was detected in the stored parity and data bits during a Flash array read operation or that a Flash array read operation returning invalid data was attempted on a Flash block that was under a Flash command operation.[1] The SFDIF flag is cleared by writing a 1 to SFDIF. Writing a 0 to SFDIF has no effect on SFDIF. 0 No single bit fault detected 1 Single bit fault detected and corrected or a Flash array read operation returning invalid data was attempted while command running

1 The single bit fault and double bit fault flags are mutually exclusive for parity errors (an ECC fault occurrence can be either single fault or double fault but never both). A simultaneous access collision (Flash array read operation returning invalid data attempted while command running) is indicated when both SFDIF and DFDIF flags are high.

2 There is a one cycle delay in storing the ECC DFDIF and SFDIF fault flags in this register. At least one NOP is required after a flash memory read before checking FERSTAT for the occurrence of ECC errors.

Table A-5. Thermal Package Characteristics[1]

Num	C	Rating	Symbol	S12GN32, S12GNA32, S12GN16, S12GNA16	S12G64, S12GA64, S12G48, S12GN48, S12GA64	S12G128, S12GA128, S12G96, S12GA96	S12G240, S12GA240, S12G192, S12GA192	Unit
48-pin QFN								
22	D	Thermal resistance single sided PCB, natural convection[2]	θ_{JA}	82				°C/W
23	D	Thermal resistance single sided PCB @ 200 ft/min[3]	θ_{JMA}	67				°C/W
24	D	Thermal resistance double sided PCB with 2 internal planes, natural convection[3]	θ_{JA}	28				°C/W
25	D	Thermal resistance double sided PCB with 2 internal planes @ 200 ft/min[3]	θ_{JMA}	23				°C/W
26	D	Junction to Board[4]	θ_{JB}	11				°C/W
27	D	Junction to Case[5]	θ_{JC}	N/A				°C/W
28	D	Junction to Package Top[6]	Ψ_{JT}	4				°C/W
64-pin LQFP								
29	D	Thermal resistance single sided PCB, natural convection[2]	θ_{JA}		70	70	70	°C/W
30	D	Thermal resistance single sided PCB @ 200 ft/min[3]	θ_{JMA}		59	58	58	°C/W
31	D	Thermal resistance double sided PCB with 2 internal planes, natural convection[3]	θ_{JA}		52	52	52	°C/W
32	D	Thermal resistance double sided PCB with 2 internal planes @ 200 ft/min[3]	θ_{JMA}		46	46	45	°C/W
33	D	Junction to Board[4]	θ_{JB}		34	34	35	°C/W
34	D	Junction to Case[5]	θ_{JC}		20	18	17	°C/W
35	D	Junction to Package Top[6]	Ψ_{JT}		5	4	N/A	°C/W
100-pin LQFP								
36	D	Thermal resistance single sided PCB, natural convection[2]	θ_{JA}			61	62	°C/W
37	D	Thermal resistance single sided PCB @ 200 ft/min[3]	θ_{JMA}			51	55	°C/W
38	D	Thermal resistance double sided PCB with 2 internal planes, natural convection[3]	θ_{JA}			49	51	°C/W
39	D	Thermal resistance double sided PCB with 2 internal planes @ 200 ft/min[3]	θ_{JMA}			43	47	°C/W
40	D	Junction to Board[4]	θ_{JB}			34	37	°C/W
41	D	Junction to Case[5]	θ_{JC}			16	17	°C/W
42	D	Junction to Package Top[6]	Ψ_{JT}			3	N/A	°C/W

Table A-7. 3.3-V I/O Characteristics (Junction Temperature From +150°C To +160°C)

Conditions are 3.15 V < V_{DD35} < 3.6 V junction temperature from +150°C to +160°C, unless otherwise noted I/O Characteristics for all I/O pins except EXTAL, XTAL,TEST and supply pins.							
Num	**C**	**Rating**	**Symbol**	**Min**	**Typ**	**Max**	**Unit**
1	M	Input high voltage	V_{IH}	0.65*V_{DD35}	—	—	V
2	T	Input high voltage	V_{IH}	—	—	V_{DD35}+0.3	V
3	M	Input low voltage	V_{IL}	—	—	0.35*V_{DD35}	V
4	T	Input low voltage	V_{IL}	V_{SS35} – 0.3	—	—	V
5	C	Input hysteresis	V_{HYS}	0.06*V_{DD35}	—	0.3*V_{DD35}	mV
6	M	Input leakage current (pins in high impedance input mode)[1] V_{in} = V_{DD35} or V_{SS35}	I_{in}	-1	—	1	µA
7	P	Output high voltage (pins in output mode) I_{OH} = –1.75 mA	V_{OH}	V_{DD35}-0.4	—	—	V
8	C	Output low voltage (pins in output mode) I_{OL} = +1.75 mA	V_{OL}	—	—	0.4	V
9	M	Internal pull up device current V_{IH} min > input voltage > V_{IL} max	I_{PUL}	-1	—	–70	µA
10	M	Internal pull down device current V_{IH} min > input voltage > V_{IL} max	I_{PDH}	1	—	70	µA
11	D	Input capacitance	C_{in}	—	7	—	pF
12	T	Injection current[2] Single pin limit Total device limit, sum of all injected currents	 I_{ICS} I_{ICP}	 –2.5 –25	—	 2.5 25	mA

1 Maximum leakage current occurs at maximum operating temperature. Current decreases by approximately one-half for each 8°°C to 12°C° in the temperature range from 50°C to 125°C.

2 Refer to Section A.1.4, “Current Injection” for more details